



Q NOTE

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JW	1	3/31/15	1 of 1

Revisions:

Rev	Originator / Date	Revised / Date	Approval / Date:	Description:
1	RPS / 3/31/15		REH 3/31/15	Originated

SOLDERABLE TERMINATION FINISHES (NO PURE TIN)

Components and components in completed subassemblies furnished under this Purchase Order shall not be received with any of the Non-Approved termination finishes listed below. The termination finish shall meet the solderability requirements of ANSI/J-STD-002 or EIA JESD22-B102 as a minimum and must accept solder at 200 degrees Celsius or less. ANSI/J-STD-002 is the preferred test method. A double tinning or dynamic solder wave process shall be used for any gold plating removal - Nickel Palladium Gold (gold flash and Electroless Nickel Immersion Gold (ENIG) are acceptable

Non-Approved Termination Finishes:

Any solder containing tin (Sn) that does not contain at least 3% lead (Pb). This includes, but not limited to:

- Pure tin (Sn)
- Tin-Bismuth (SnBi)
- Tin-Silver-Copper (SnAgCu a.k.a. SAC105, 305, 405 and all other variations)
- Tin-Silver (SnAg) Gold that is:
 - Greater than 0.4 μm [15.7 microinches] thick on a surface mount part
 - Greater than 2.5 μm [98.4 microinches] thick on a thru-hole part

Exception: Tin-Silver (SnAg) and Tin Antimony (SnSb) may be approved for use in high temperature solder applications.

This document is an integral part of the contract (purchase order), which calls it out. The revision in effect at the time the purchase order was placed applies.